

# 2SC1509

### Silicon NPN epitaxial planar type

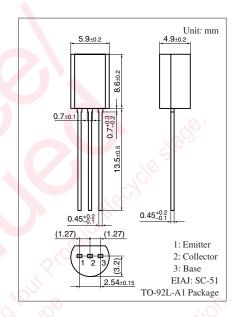
For low-frequency driver amplification Complementary to 2SA0777 (2SA777)

#### ■ Features

- High collector-emitter voltage (Base open) V<sub>CEO</sub>
- Optimum for the driver stage of a low-frequency and 25 W to 30 W output amplifier

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	80	V	
Collector-emitter voltage (Base open)	$V_{CEO}$	80	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V	
Collector current	$I_{C}$	0.5	A	
Peak collector current	$I_{CP}$	1	A	
Collector power dissipation	P <sub>C</sub>	750	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



### ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

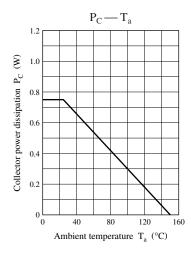
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu\text{A}, I_E = 0$	80	95		V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 100  \mu A,  I_B = 0$	80			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10  \mu A,  I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	130		330	_
	h <sub>FE2</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 500 \text{ mA}$	50	100		_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.2	0.4	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.85	1.2	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_{E} = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11	20	pF

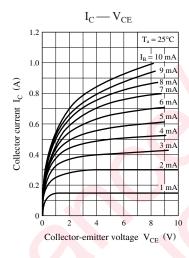
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

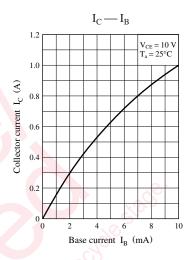
#### 2. \*: Rank classification

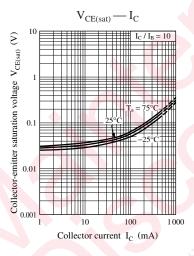
Rank	R	S	
h <sub>FE1</sub>	130 to 220	220 185 to 330	

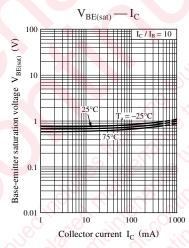
Note) The part number in the parenthesis shows conventional part number.

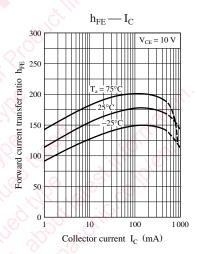


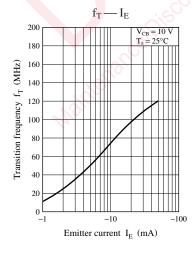




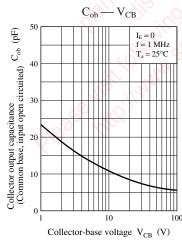


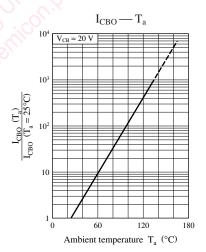


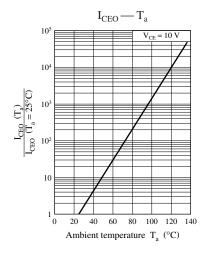


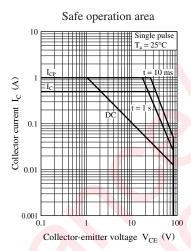


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